

AMENDMENTS TO THE CLAIMS

1-12. (canceled).

13. (previously amended) A method of making an FED having a central active display area and a surrounding peripheral area, comprising:

making a cathode assembly,

making an anode assembly, and

assembling said cathode and anode assemblies,

wherein said step of making a cathode assembly includes the step of locally applying an etchant to uncover a structure in the peripheral area of the cathode assembly.

14. (original) The method of Claim 13 wherein said structure comprises an alignment mark.

15. (original) The method of Claim 13 wherein said structure comprises a bond pad.

16. (original) The method of Claim 13 wherein said step of locally applying an etchant comprises spraying a wet etchant on the structure without spraying the etchant elsewhere.

17. (currently amended) A method of making an FED having a central active display area and a surrounding peripheral region, comprising:

making a cathode assembly,

making an anode assembly, and

assembling said cathode and anode assemblies,

wherein said step of making an anode assembly includes the step of locally applying an etchant to uncover a structure in the peripheral region of the ~~cathode~~ anode assembly.

18. (original) The method of Claim 17 wherein said structure comprises an alignment mark.

19. (original) The method of Claim 17 wherein said step of locally applying an etchant comprises spraying a wet etchant on the structure while limiting spraying of the etchant elsewhere.

20. (original) A method of forming a cathode assembly of an FED, comprising:

- providing a substrate having a central area and a peripheral area;
- forming alignment marks on the peripheral area of the substrate;
- forming an emitter electrode structure on the central area of the substrate;
- forming a plurality of micropoints in groups on the emitter electrode structure;
- depositing an insulating layer over the substrate, emitter electrode structure, and plurality of micropoints;
- depositing a conductive layer over the insulating layer;
- locally applying etchant on the alignment marks; and
- selectively etching openings through the conductive and insulating layers to expose the micropoints, with walls defining the openings being spaced away from the micropoints.

21. (original) The method of Claim 20 wherein selectively etching openings through the conductive and insulating layers comprises applying a layer of photoresist on said conductive layer, imaging said photoresist to define a pattern for said openings, developing the photoresist, and etching the pattern for the openings.

22. (original) The method of Claim 21 further comprising the step of polishing the conductive layer after the step of depositing a conductive layer over the insulating layer.

23. (original) The method of Claim 22 wherein said step of polishing comprises chemical-mechanical planarization.

24. (original) The method of Claim 21 wherein said step of locally applying an etchant comprises spraying a wet etchant on the alignment marks without spraying the etchant elsewhere.

25. (original) A method of forming a cathode assembly of a field emission device, comprising:

providing a substrate;

making alignment marks in a peripheral region of the substrate;

forming an emitter electrode structure on a central region of the substrate, said central region being substantially surrounded by the peripheral region;

forming a plurality of micropoints on the emitter electrode structure;

depositing an insulating layer over the substrate, emitter electrode structure, and plurality of micropoints;

depositing a first conductive layer over the insulating layer;

polishing the conductive layer;

selectively applying localized etchant on the alignment marks while inhibiting application of the etchant on the central region to clear the marks of material deposited thereon; and

etching openings through the conductive and insulating layers to expose the micropoints, with walls defining the openings being spaced away from the micropoints.

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26. (original) The method of Claim 25 wherein said step of selectively applying a localized etchant comprises spraying a wet etchant on the alignment marks.

27-32. (canceled).